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(54) **SEMICONDUCTOR ASSEMBLY
COMPRISING A 3D BLOCK AND METHOD
OF MAKING THE SAME**

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ABSTRACT

A method of making an assembly or package comprising 3D blocks may include forming a conductive element horizontally oriented over a first carrier, forming support material around the conductive element, and singulating the conductive element and the support material to form a plurality of 3D blocks. The method may further include rotating each of the plurality of 3D blocks and mounting the plurality of 3D blocks over a second carrier with the conductive traces of the 3D blocks vertically oriented to form a vertically oriented conductive element. A plurality of components may be disposed laterally offset from each of the plurality of 3D blocks, an encapsulant may be disposed thereover to form a reconstituted panel that may be singulated to form a plurality of individual assemblies.

